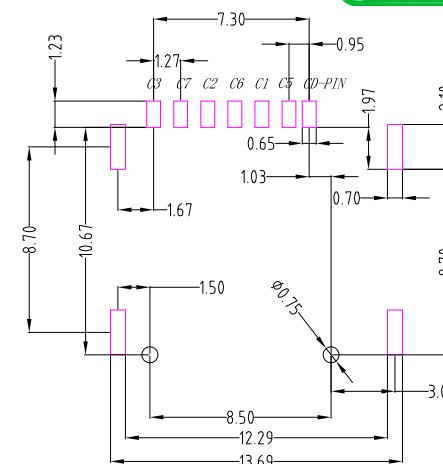
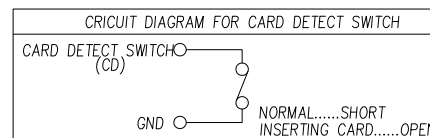




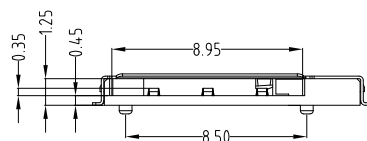
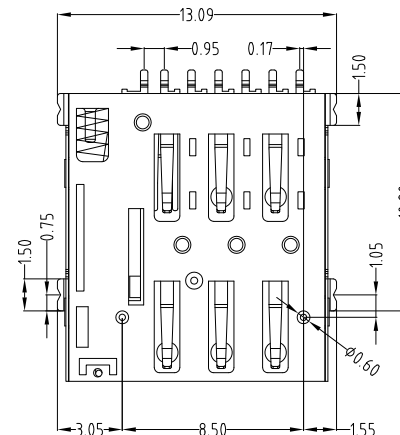
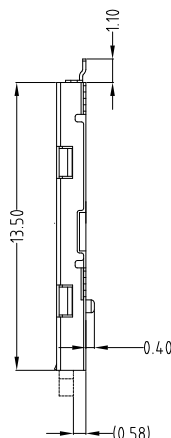
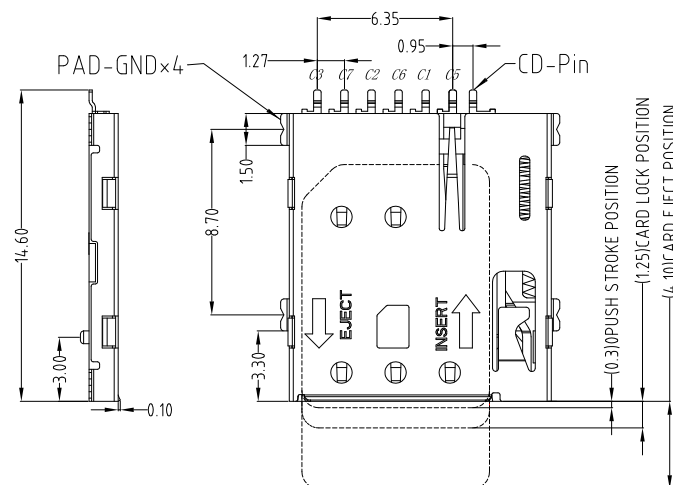
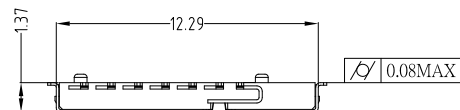
P.C.B LAYOUT

SPECIFICATION:

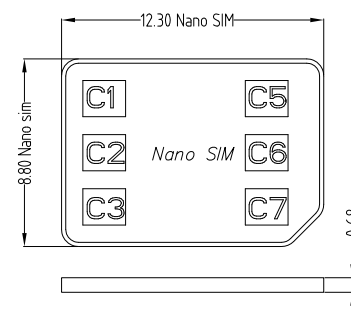
1. CURRENT RATING : 0.5A MAX.
2. VOLTAGE RATING : 125V AC / DC
3. INSULATION RESISTANCE : 1000M Ω MIN.
4. CONTACT RESISTANCE : 100m Ω MAX.
5. OPERATING TEMPERATURE RANGE : -40°C TO +80°C.
6. STORAGE TEMPERATURE RANGE : -20°C TO +70°C.

MATERIALS:

1. HOUSING : LCP
 2. CONTACT : PHOSPHOR BRONZE
 3. SHELL : SUS
- Finish:
1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
 2. SHELL: NICKEL UNDER PLATED SURFACE LAYER



SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5	± 0.2
Above 5 ~ 15	± 0.3
Above 15 ~ 30	± 0.4
Above 30 ~ 50	± 0.5
Angle	± 0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:
Jack Lu
12/27/23

CHECKED BY:
Jacky Chen
12/27/23

APPROVED BY:
Tony Kao
12/27/23

MAT'L	TITLE	CONNECTOR
FINISH	MODLE	Nano SIM CARD PUSH PUSH H1.37
SCALE	DWG NO.	NSIM-019107A-S267
SHEET NO.	PART NO.	NSIM-019107A-S267

SIZE
A4
VER
R